

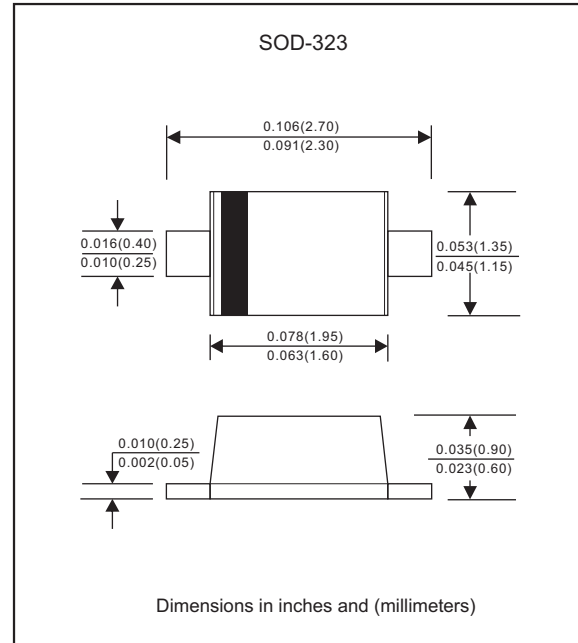
Features

- Low current rectification and high speed switching.
- Extremely small surface mount type.
- Up to 500mA current capability.
- Low forward voltage drop .
- Silicon epitaxial planar chip, metal silicon junction.
- Lead-free parts meet exceeds environmental standards of MIL-STD-19500 /228
- Compliant to Halogen-free

Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-323
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any

Package outline



Maximum ratings and Electrical Characteristics (AT T_A=25°C unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Repetitive peak reverse voltage		V _{RM}			30	V
Continuous reverse voltage		V _R			20	V
Mean rectifying current		I _O			500	mA
Forward surge current		I _{FSM}			5000	mA
Operating junction temperature range		T _J	-55		+125	°C
Storage temperature range		T _{STG}	-55		+125	°C
Forward voltage	I _F = 500 mA	V _F			0.47	V
Reverse current	V _R = 20 V	I _R			100	uA

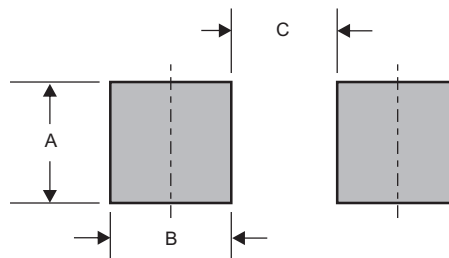
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type numbe	Marking code
RB551V-30	C1

Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-323	0.032 (0.82)	0.022 (0.56)	0.069 (1.75)

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOD-323	7"	3000	4.0	30,000	195*195*150	178	460*400*420	360,000	14.8